

L Number	Hits Search Text	DB	Time stamp
1	215 smart with label	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 10:55
2	10837 smart with card	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 10:55
3	80712 (flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 10:57
4	19830 hard with particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 10:57
5	719715 flip bumps balls flipchip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:03
6	556 (hard with particles) same (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:02
7	2 ((hard with particles) same (flip bumps balls flipchip)) and (smart with label)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:02
8	10 (smart with card) and (hard with particles)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:05
9	733 (smart with card) and (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:14
10	567 ((smart with card) and (flip bumps balls flipchip)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:15
11	83 (((smart with card) and (flip bumps balls flipchip)) and (chip flip)) and particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:06
12	25 (smart with label) and (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:14
13	22 ((smart with label) and (flip bumps balls flipchip)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:23

14	11882	((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:23
15	4838	((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:23
16	4838	((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)) and ((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:23
17	55	((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)) and (hard with particles)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:24